

FIG 1

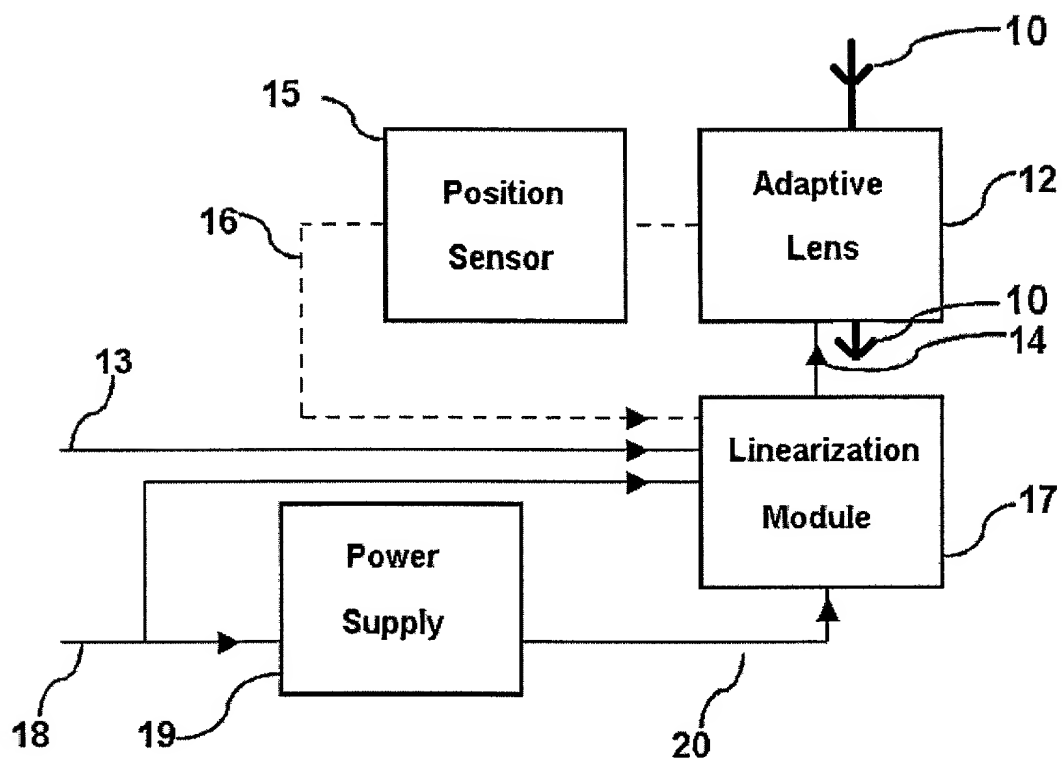


FIG.2

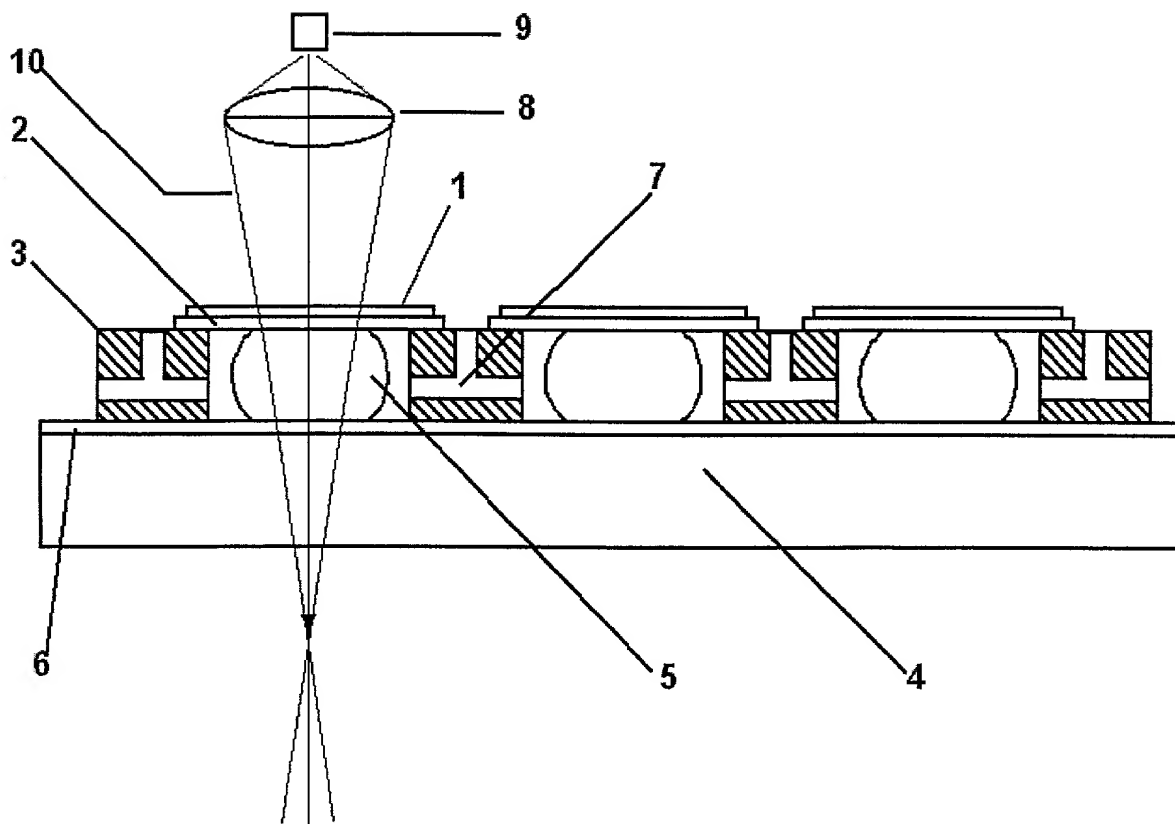


FIG. 3

FIG. 4 is a cross-sectional view of the device of FIG. 1, showing the device in a cross-sectional view. The device includes a substrate 4, a layer 5, a layer 6, a layer 7, a layer 8, a layer 9, and a layer 10. The device is shown in a cross-sectional view, with the layers 4, 5, 6, 7, 8, 9, and 10 being stacked on top of each other. The layer 4 is the bottom layer, and the layer 10 is the top layer. The layer 5 is a thin layer, and the layer 6 is a thicker layer. The layer 7 is a thin layer, and the layer 8 is a thicker layer. The layer 9 is a thin layer, and the layer 10 is a thicker layer. The device is shown in a cross-sectional view, with the layers 4, 5, 6, 7, 8, 9, and 10 being stacked on top of each other. The layer 4 is the bottom layer, and the layer 10 is the top layer. The layer 5 is a thin layer, and the layer 6 is a thicker layer. The layer 7 is a thin layer, and the layer 8 is a thicker layer. The layer 9 is a thin layer, and the layer 10 is a thicker layer.

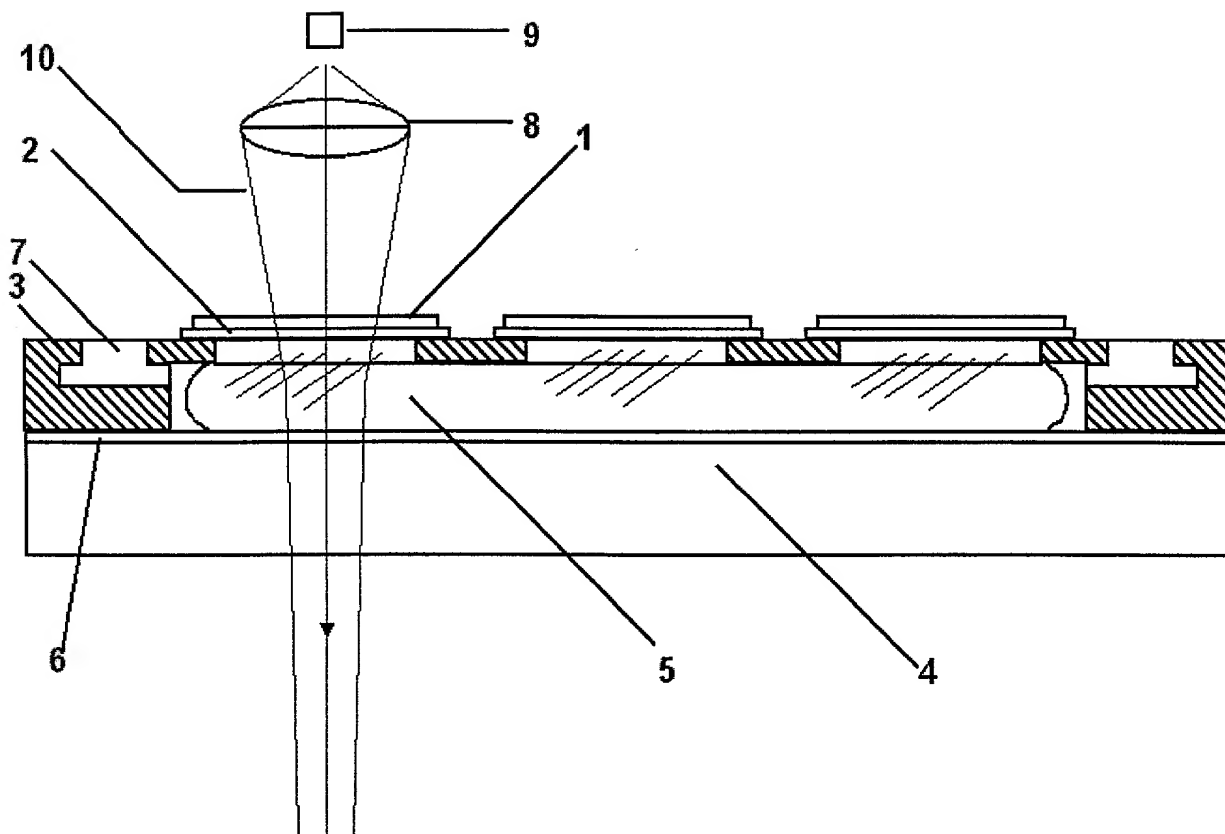


FIG. 4